



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC016N06NSSC	Issued	16. May 2021
MA#	MA005348448		
Package	PG-WSON-8-2	Weight*	99.97 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.124	2.12	2.12	21249	21249
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		114	
	non noble metal	zinc	7440-66-6	0.046	0.05		456	
	non noble metal	iron	7439-89-6	0.912	0.91		9121	
	non noble metal	copper	7440-50-8	37.021	37.03	38.00	370335	380026
wire	noble metal	gold	7440-57-5	0.063	0.06	0.06	628	628
encapsulation	organic material	carbon black	1333-86-4	0.038	0.04		377	
	plastics	epoxy resin	-	1.735	1.74		17353	
	inorganic material	silicondioxide	60676-86-0	17.083	17.09	18.87	170887	188617
leadfinish	non noble metal	tin	7440-31-5	1.365	1.37	1.37	13654	13654
plating	noble metal	silver	7440-22-4	0.839	0.84	0.84	8388	8388
solder	noble metal	silver	7440-22-4	0.056	0.06		562	
	non noble metal	tin	7440-31-5	0.112	0.11		1125	
	non noble metal	lead	7439-92-1	2.080	2.08	2.25	20808	22495
heat sink clip	inorganic material	phosphorus	7723-14-0	0.011	0.01		109	
	non noble metal	zinc	7440-66-6	0.044	0.04		438	
	non noble metal	iron	7439-89-6	0.876	0.88		8759	
	non noble metal	copper	7440-50-8	35.552	35.56	36.49	355637	364943
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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